

3711/04

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Complete if Known		
				Application Number	10/799,204	
Sheet		1	of	3	Filing Date	3/11/2004
					First Named Inventor	Joan K. Vrtis
					Art Unit	2835 3729
					Examiner Name	Tai, Gould P. TAI V NGUYEN
					Attorney Docket Number	42P13111D

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No.†	Document Number	Publication Date Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code* (if known)			
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		US-4,858,073	08-15-1989	Gregory	
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FOREIGN PATENT DOCUMENTS					
Examiner Initials*	Cite No.†	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Country Code* - Number* - Kind Code* (if known)			

Examiner Signature	<i>Tai Nguyen</i>	Date Considered	4/19/05
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*Applicant's unique citation designation number (optional). *See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. *Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). *For Japanese patent documents, the indication of the year of reign of the Emperor must precede the serial number of the patent document. *Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. *Applicant is to place a check mark here if English language Translation is attached.

Based on PTO/SB/08A (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wtr) 08/11/2003.

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Sheet 2 of 3				Filing Date	3/11/2004
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				Art Unit	2835 3729
				Examiner Name	Tolun, Gerard TAI V NGUYEN
				Attorney Docket Number	42P13111D

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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TN		PARQUET, D., ET AL., OSP: The High Performance Surface Finish, Electronic Interconnect Conference, 1997.	

Examiner Signature	<i>Gerard T. Tolun</i>	Date Considered	4/19/05
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Sheet	3	of	3	Attorney Docket Number	42P13111D

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Examiner Initials*	Cite No.†	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T‡
TN		ROMM, D., ET AL., Evaluation of Ni/Pd-Finished ICs with Lead Free Solder Alloys, Texas Instruments Application Report SZZA024, Jan. 2001.	
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		Double Sided 4Mb SRAM Coupled Cap PBGA Card Assembly Guide, IBM Application Note, Feb. 1998.	
TN		Kester Solder Paste for Surface Mount and General Electronics Assemblies, Online Catalog of Preferred Products, 2001.	

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